

ABSTRACT

Method and structure for securing a mold compound to a printed circuit board is disclosed. A through hole or a blind hole is fabricated in a printed circuit board adjacent to a die. The hole is then filled with a mold compound. The mold compound also surrounds and covers the die. The mold compound within the hole locks the mold compound to the surface of the printed circuit board. In one embodiment, a through hole or a blind hole is fabricated adjacent to a semiconductor die. The semiconductor die is attached to a layer of gold-plated copper on the printed circuit board. After the semiconductor die is attached to the layer of gold-plated copper on the printed circuit board, the semiconductor die is surrounded and covered by the mold compound and the fabricated hole is filled with the mold compound. The mold compound within the hole has good adhesion to the resin layer which constitutes the printed circuit board. This adhesion locks the mold compound securely to the surface of the printed circuit board.

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